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(54) DIE-BONDING DEVICE

(57) Abstract:

PROBLEM TO BE SOLVED: To facilitate the setting operation of a bonding arm before the die-bonding operation by a die-bonding device.

SOLUTION: A contact sensor 27, which detects the upward movement of the bonding arm 13 in a chip attraction tool 18, is provided on the bonding arm 13. Based on the position of the vertical movement of the bonding arm 13 at the point of time when the contact sensor 27 detected the upward movement of the tool 18, the vertical movement of the bonding arm 13, when a chip is attracted and bonding position is conducted, is controlled, and the setting operation of the movement position of the bonding arm 13 is unnecessary.

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